

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An electrostatic chuck having a bonded structure comprising a ceramic ~~electrostatic chuck member~~ having an electrode in direct contact ~~therewith~~ with said ceramic member, a metal member, and a bonding layer, said ceramic ~~electrostatic chuck member~~ and said metal member being bonded with said bonding layer;

wherein said bonding layer comprises at least a first outermost bonding layer bonded to said ceramic ~~electrostatic chuck member~~, a second outermost bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost bonding layers, and wherein each of said first and second outermost bonding layers comprises a silicone layer.

2. (Previously Presented) The electrostatic chuck according to claim 1, wherein the thickness of said bonding layer is in a range of 0.05 to 0.5 mm.

3. (Currently Amended) The electrostatic chuck according to claim 1, wherein said ceramic ~~electrostatic chuck member~~ comprises an aluminum nitride base material formed as an integrated body by sintering said base material with said electrode embedded therein.

4. (Currently Amended) The electrostatic chuck according to claim 1, wherein an adsorption surface of said ceramic ~~electrostatic chuck member~~ has a flatness of 30 μm or less.

5. (Cancelled).

6. (Currently Amended) The electrostatic chuck according to claim 1, wherein said electrode is embedded in said ceramic ~~electrostatic chuck~~ member.
7. (Cancelled).
8. (Currently Amended) An electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member, and a bonding layer bonding said ceramic electrostatic chuck member and said metal member, said bonding layer ~~comprising only~~ consisting of a first outermost silicone bonding layer bonded to said ceramic electrostatic chuck member, a second outermost silicone bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost silicone bonding layers.
9. (Previously Presented) The electrostatic chuck according to claim 8, further comprising an electrode embedded in said ceramic electrostatic chuck member.
10. (Cancelled).
11. (Cancelled).